

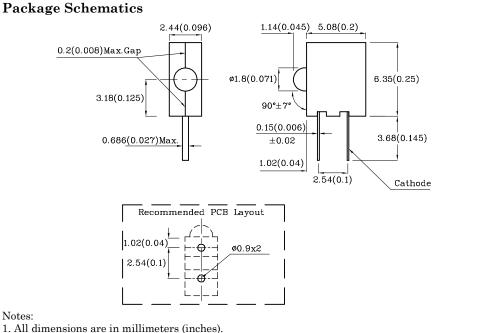
Part Number: XNH1ZMG46D

1.8mm One Position CBI Housing

Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- \bullet Reliable & robust
- RoHS Compliant





Notes:

2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Green (GaP)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V		
Forward Current	$I_{\rm F}$	25	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA		
Power Dissipation	\mathbf{P}_{D}	62.5	mW		
Operating Temperature	$T_{\rm A}$ -40 ~ +85		°C		
Storage Temperature	Tstg	$-40 \sim +85$	-0		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

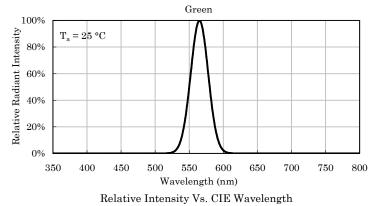
Operating Characteristics (T _A =25°C)	Green (GaP)	Unit	
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2.2	V
Forward Voltage (Max.) (I _F =20mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	μΑ
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

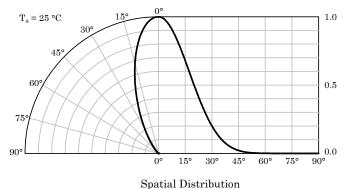
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XNH1ZMG46D	Green	GaP	Green Diffused	5*	11*	565*	40°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

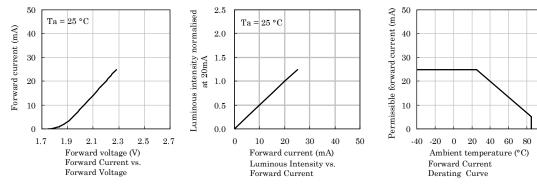


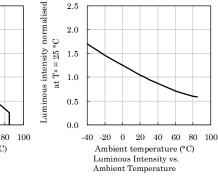
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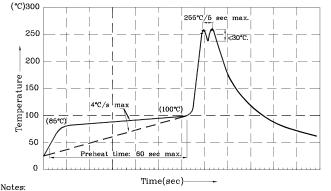


& Green





Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C. 4.Fixtures should not incur stress on the component when mounting and during process.

during soldering process. 5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

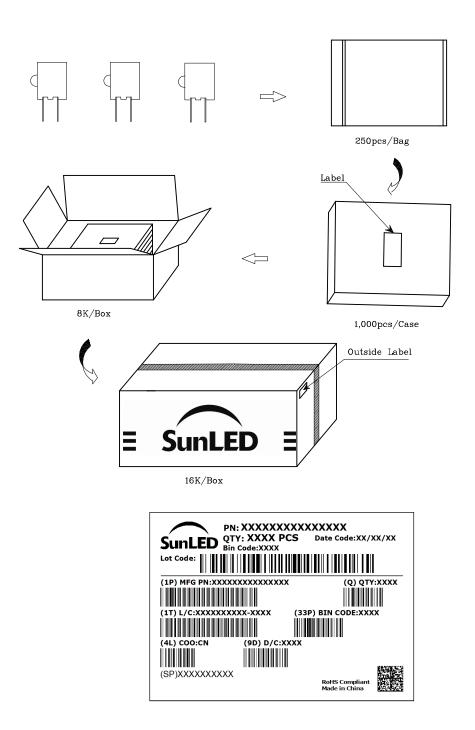
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



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- 6. Additional technical notes are available at https://www.SunLEDusa.com/TechnicalNotes.asp

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